MAJOR TELECOM COMPANY

LDS ANTENNA ARRAY

AVIENT SOLUTION

Edgetek[™] ET9600-8015 Formulation

WHY AVIENT

- Provided high-heat material to enable miniaturization and multi-function integration for an innovative 3D design
- Formulated LDS solution with low dielectric constant (Dk 3.98) and dissipation factor (Df 0.006) values

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- Required material suitable for Laser Direct Structuring (LDS) for a 3D antenna design that allowed Surface Mount Technology (SMT) for mass production in a short manufacturing time
- 265°C /10 seconds